AMENDMENTS TO THE CLAIMS

Docket No.: 13194-00160-US

- 1. (Currently amended) A process for making a refractory metal part comprising:
- (a) loading <u>refractory</u> powder metal particles into a hopper for feeding into a laser additive chamber, <u>wherein the refractory metal particles are selected from the group consisting of tantalum</u>, Re, W, Mo, W alloys, Mo alloys, Re alloys, niobium, tantalum alloys and niobium alloys,
 - (b) loading a substrate into the laser additive chamber,
- (c) feeding the powder metal powders into the additive chamber onto successive points on the substrate in a linear trace,
- (d) melting the substrate and the powder with a laser beam and building up multiple coatings of a controlled microstructure,
- (e) tracing the substrate over a selected area with a combined deposition and melt beam and building up a coating of a controlled microstructure in multiple layers, and
- (f) building up a deposit from the coating and forming a refractory metal part and wherein the refractory metal part is a sputtering target or tube perform or furnace part preform.
- 2. (Original) The process of Claim 1, wherein the deposit built up from the coating is a fully dense deposit.
- 3. (Original) The process of Claim 1, wherein the process is carried out under inert conditions.
- 4. (Original) The process of Claim 3, wherein the conditions include argon, at or near or below atmospheric pressure.
- 5. (Original) The process of Claim 1, wherein the process is carried out under a hard vacuum.
- 6. (Original) The process of Claim 1, wherein the laser beam generates sufficiently high heat to create conditions that purify the powder and the refractory metal part.
- 7. (Original) The process of Claim 1, wherein the refractory metal part is a sputtering target.

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8. (Original) A refractory metal part made by the process of Claim 1.

9. (Withdrawn) A method for rejuvenating a tantalum sputtering target comprising subjecting an eroded region of a tantalum sputtering target to plasma deposition, forming a fully dense coating, and thereby rejuvenating the tantalum sputtering target.

- 10. (Withdrawn) The method of Claim 9, wherein the tantalum sputtering target has a backing plate and the target is rejuvenated without debonding the backing plate from the target.
- 11. (Withdrawn) A sputtering target made by the method of Claim 9.
- 12. (Withdrawn) A method for rejuvenating a tantalum sputtering target comprising subjecting an eroded region of a tantalum sputtering target to laser sintering, forming a fully dense coating, thereby rejuvenating the tantalum sputtering target.
- 13. (Withdrawn) The method of Claim 12, wherein the tantalum sputtering target has a backing plate and the target is rejuvenated without debonding the backing plate from the target.
- 14. (Withdrawn) A sputtering target made by the method of Claim 12.
- 15. (Canceled)
- 16. (Canceled)
- 17. (New) The process of Claim 1, wherein the refractory metal powder particles are tantalum or tantalum alloys.
- 18. (New) The process of Claim 1, wherein the substrate is a tantalum plate.

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19. (New) The process of Claim 1, wherein the refractory metal part is a sputter plate bonded to a backing plate.

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- 20. (New) The process of Claim 1, wherein the sputter plate is a tantalum sputter plate, and the refractory metal particles are tantalum or tantalum alloys.
- 21. (New) A process for making a refractory metal part comprising:
- (a) loading powder metal particles into a hopper for feeding into a laser additive chamber,
 - (b) loading a tantalum substrate into the laser additive chamber,
- (c) feeding the powder metal powders into the additive chamber onto successive points on the substrate in a linear trace,
- (d) melting the substrate and the powder with a laser beam and building up multiple coatings of a controlled microstructure,
- (e) tracing the substrate over a selected area with a combined deposition and melt beam and building up a coating of a controlled microstructure in multiple layers, and
 - (f) building up a deposit from the coating and forming a tantalum sputtering target.
- 22. (New) The process of Claim 21, wherein the refractory metal particles are selected from the group consisting of tantalum and tantalum alloys.

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